
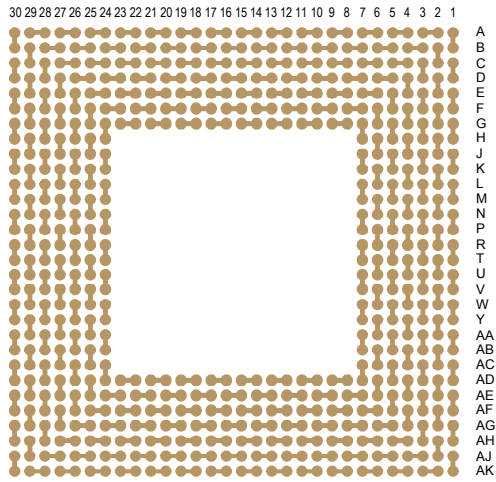


- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
  - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
  - 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
  - 4) SOLDER MASK DEFINED PAD OPENING: 0.22mm [8.7MIL].
  - 5) PAD Cu DIAMETER: 0.305mm [12 MIL].
  - 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
  - 7) DUMMY DIE IS OPTIONAL.
  - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
  - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

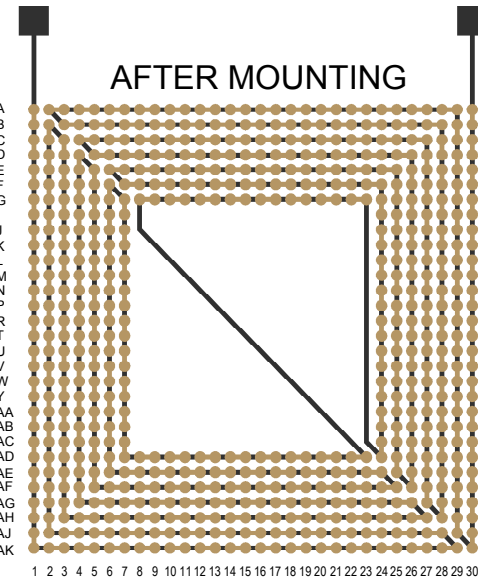
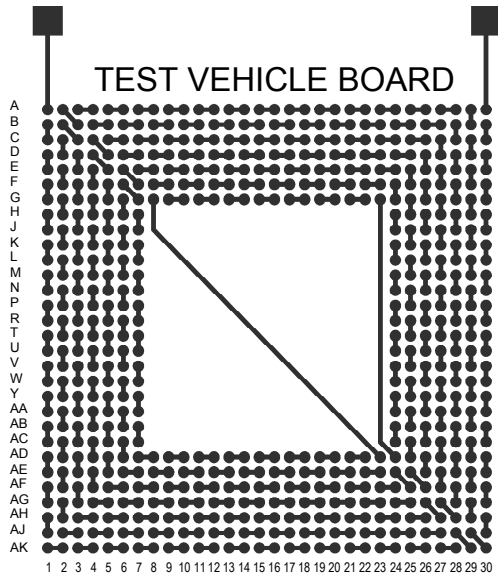
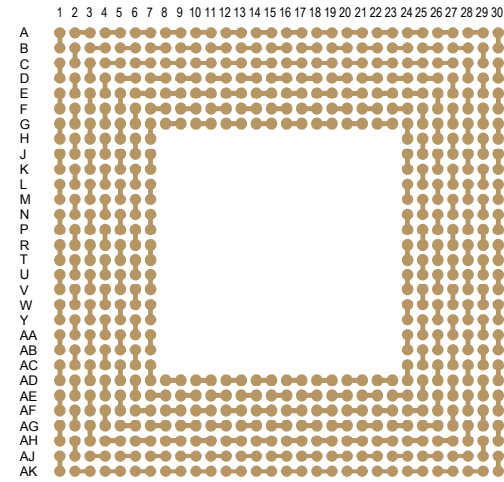
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA644T.4C-DC305D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA644T.4-DC305D	Sn63/Pb37	NO	NO	YES

APPROVALS		DATE			
DRAWN	T. Au	12/21/12			
ENG	M. Hart	12/21/12	SCALE		SIZE A
MFG			DRAWING NO.		543051
QA			REV		A
CUST			DO NOT SCALE DRAWING		SHEET 1 OF 2
REVISED					

### BALL VIEW



### BOTTOM SIDE (TOP X-RAY VIEW)



**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.305mm [12MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm [5 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.22mm [8.7 MIL].

<b>TopLine®</b>			
TITLE		BGA644T.4-DC305 DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
	A	543051	A
DO NOT SCALE DRAWING			SHEET 2 OF 2